

Title (en)

STACKED POLISHING PAD FOR HIGH TEMPERATURE APPLICATIONS

Title (de)

GESTAPELTE POLIERSCHEIBE FÜR HOCHTEMPERATURANWENDUNGEN

Title (fr)

TAMPON À POLIR À COUCHES EMPILÉES POUR DES APPLICATIONS HAUTE TEMPÉRATURE

Publication

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Application

EP 08754175 A 20080501

Priority

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- US 74392207 A 20070503

Abstract (en)

[origin: US2008274674A1] The invention provides a polishing pad for chemical-mechanical polishing comprising a polishing layer, a bottom layer, and a hot-melt adhesive, the hot-melt adhesive joining together the polishing layer and the bottom layer. The hot-melt adhesive comprises between about 2 and about 18 wt. % EVA and is substantially resistant to delamination when the polishing layer attains a temperature of about 40° C. The invention also provides a method of polishing a substrate with the aforementioned polishing pad, as well as a method of preparing such a polishing pad.

IPC 8 full level

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